

DAP236U

Diode, array, band switching, surface mount

This small surface mount package contains two diodes in parallel. It is suitable for high density surface mounting on a printed circuit board.

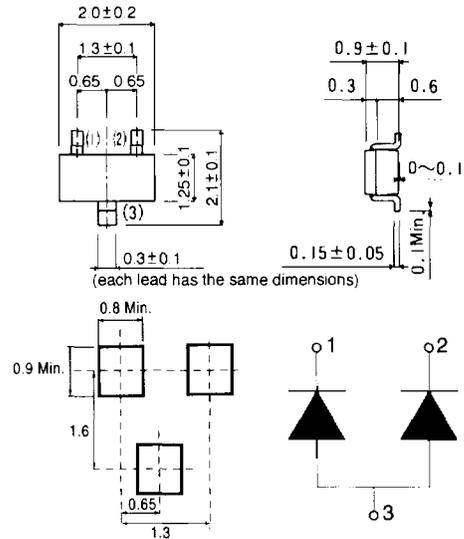
Features

- available in UMD3 (UMD, SC-70, SOT-323) package
- part marking, letter X

Applications

- high frequency switching

Dimensions (Units : mm)



Absolute maximum ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
DC reverse voltage	V_R	35	V
Power dissipation	P_d	150	mW
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	$-55 \sim +125$	$^\circ\text{C}$

Electrical characteristics (unless otherwise noted, $T_a = 25^\circ\text{C}$)

Parameter	Symbol	Min	Typical	Max	Unit	Conditions
Forward voltage	V_F		0.87	1.0	V	$I_F = 10$ mA
Reverse current	I_R		0.01	10	nA	$V_R = 25$ V
Capacitance between terminals	C_t		0.80	1.2	pF	$V_R = 6$ V, $f = 1$ MHz
Forward operating resistance	r_F		0.60	0.9	Ω	$I_F = 2$ mA, $f = 100$ MHz

Electrical characteristic curves

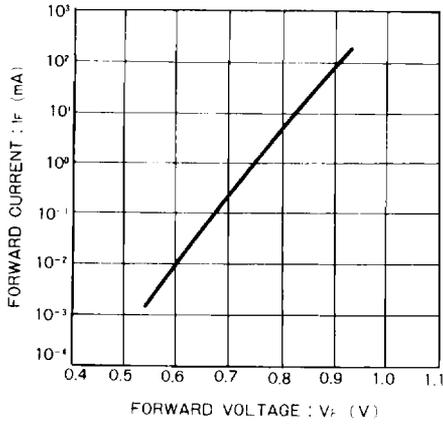


Figure 1

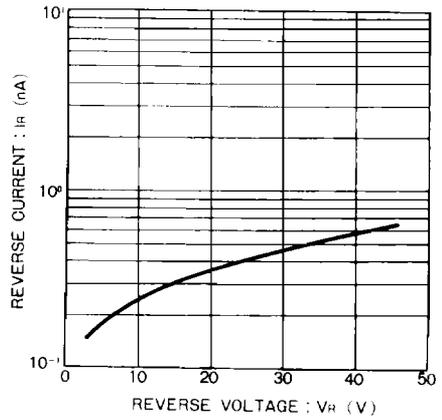


Figure 2

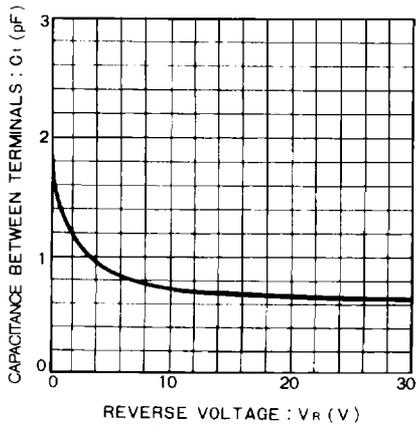


Figure 3

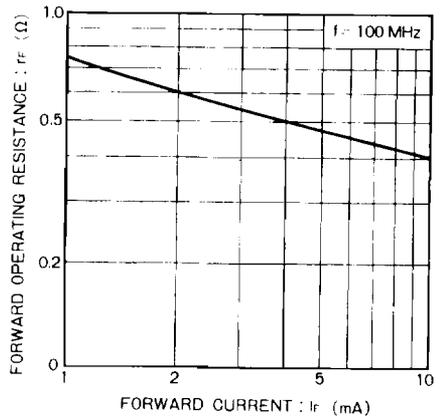


Figure 4